



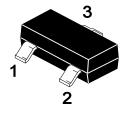
# N- Enhancement Mode Field Effect Transistor

#### **Features**

Arr R<sub>DS(ON)</sub> < 85mΩ @V<sub>GS</sub> = 10V R<sub>DS(ON)</sub> < 120mΩ @V<sub>GS</sub> = 4.5V V<sub>DS</sub>=60V, I<sub>D</sub>=2A

◆ High power and current handing capability

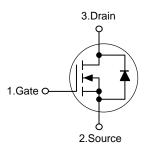
### SOT-23



### Schematic diagram

# **Applications**

- ♦ DC/DC Converter
- Battery Switch



# **Absolute Maximum Ratings**

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	V
Continuous Drain Current	I <sub>D</sub>	2	А
Pulsed Drain Current Note1	Ірм	10	А
Total Power Dissipation	$P_D$	0.9	W
Operating Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>STG</sub>	- 55 to + 150	°C

### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient Note2	$R_{ hetaJA}$	139	°C/W

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# N- Enhancement Mode Field Effect Transistor

# **Electrical Characteristics** (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Туре	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	I <sub>DSS</sub> V <sub>DS</sub> =60V,V <sub>GS</sub> = 0V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V			±100	nA
Gate Threshold Voltage Note3	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.3	2	V
	5	V <sub>GS</sub> =10V, I <sub>D</sub> =3A			105	0
Drain-Source On-Resistance Note3	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A			125	mΩ
Forward Tranconductance Note3	<b>g</b> FS	V <sub>DS</sub> =15V, I <sub>D</sub> =2A		3		S
Dynamic Characteristics						
Input Capacitance	C <sub>iss</sub>			510		pF
Output Capacitance	Coss	$V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$		34		
Reverse Transfer Capacitance	C <sub>rss</sub>			26		
SWITCHING Characteristics						
Total Gate Charge	$Q_g$			7.5		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 30V, I_{D} = 3A, V_{GS} = 4.5V$		1.4		nC
Gate-Drain Charge	$Q_{gd}$			3		ı
Turn-On Delay Time	t <sub>d(on)</sub>			6		
Turn-On Rise Time	t <sub>r</sub>	$V_{GS}=10V, V_{DD}=30V, I_{D}=1.5A, R_{G}=1\Omega$		15		
Turn-Off Delay Time	t <sub>d(off)</sub>	VGS-10V,VDD-30V,ID-1.3A,RG-112		15		ns
Turn-Off Fall Time	t <sub>f</sub>	]		10		
Source-Drain Diode characteristics	•		ı		<u>.                                    </u>	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> =3A,V <sub>GS</sub> =0V			1.2	V

#### Notes:

- 1. Repetitive rating: Pulse width limited by junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test : Pulse Width≤300µs, Duty Cycle≤2%.



# **Typical Characteristics Curves**

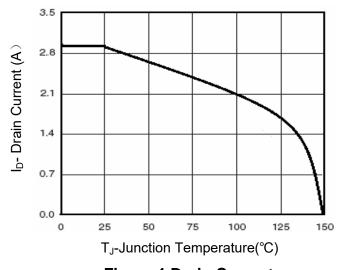


Figure 1 Drain Current

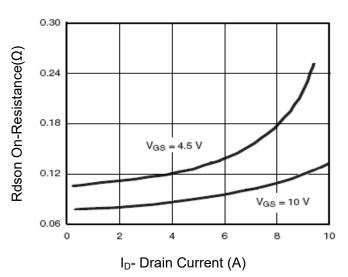


Figure 3 Drain-Source On-Resistance

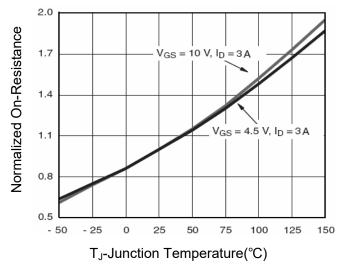
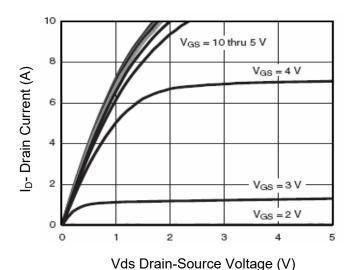


Figure 5 Drain-Source On-Resistance



**Figure 2 Output Characteristics** 

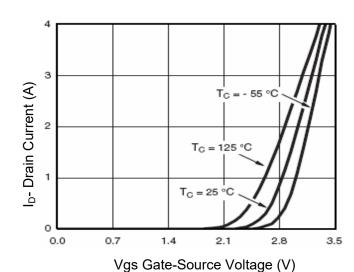


Figure 4 Transfer Characteristics

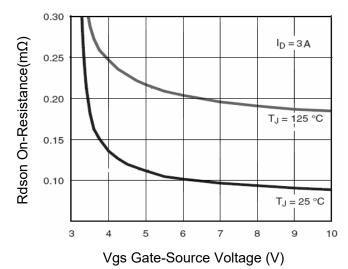


Figure 6 Rdson vs Vgs

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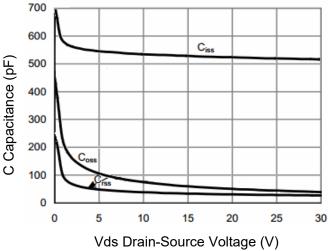


Figure 7 Capacitance vs Vds

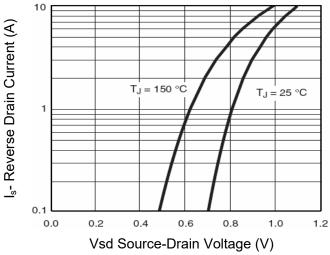


Figure 9 Source- Drain Diode Forward

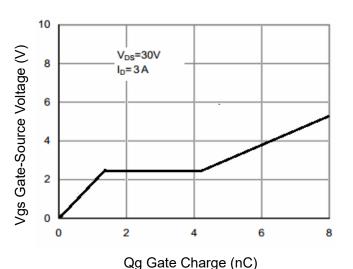


Figure 8 Gate Charge

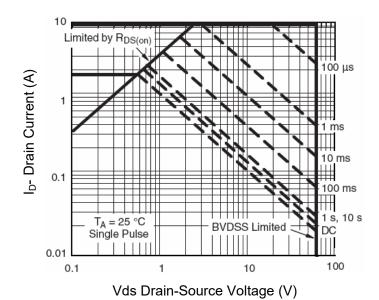


Figure 10 Safe Operation Area

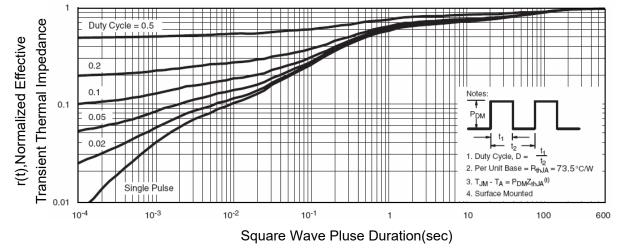


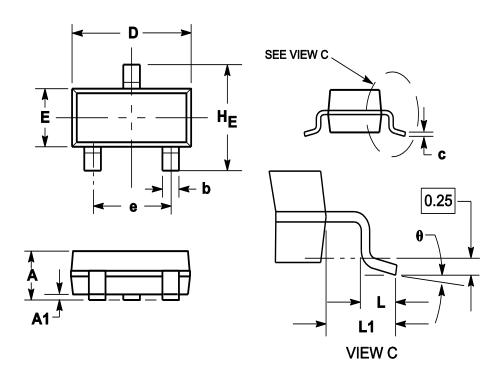
Figure 11 Normalized Maximum Transient Thermal Impedance

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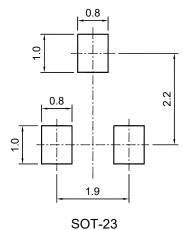


# **Package Outline**

### **SOT-23**



	Dim	ensions in millime	ter
Symbol	Min.	Тур.	Max.
А	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
С	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
HE	2.250	2.400	2.550
е	1.800	1.900	2.000
L1		0.550REF	
L	0.300		0.500
θ	00		80



Recommended soldering pad

# **Ordering Information**

Device	Package	Shipping
PJM02N60SA	SOT-23	3000/Reel&Tape(7inch)

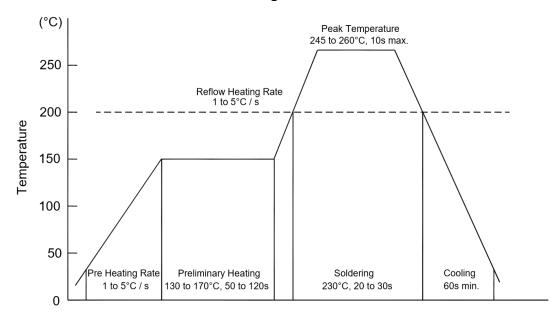
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# **Conditions of Soldering and Storage**

#### Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

#### Conditions of hand soldering

Temperature: 370 °C

Time: 3s max. Times: one time

#### Storage conditions

**Temperature** 

5 to 40 °C

**Humidity** 

30 to 80% RH

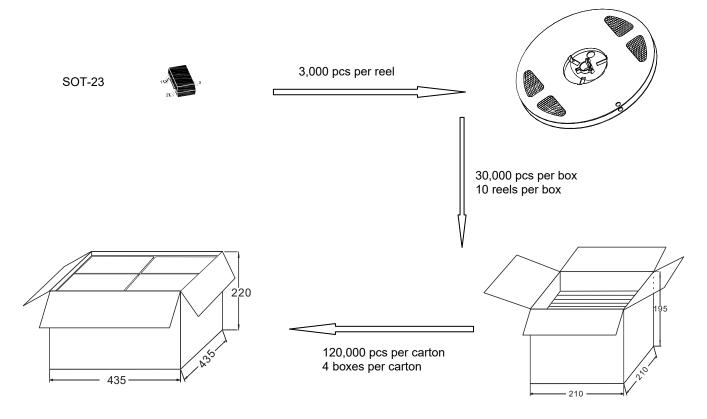
Recommended period

One year after manufacturing

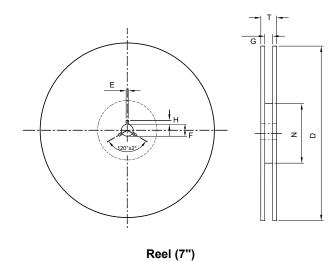


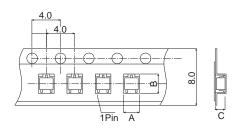
# **Package Specifications**

# ♦ The method of packaging



### ♦ Embossed tape and reel data





Tape (8mm)

Symbol	Value (unit: mm)
Α	3.15 ± 0.1
В	2.7 ± 0.1
С	1.25 ± 0.1
E	2 ± 0.5
F	13 ± 0.5
D	178 ± 2.0
G	8.4 ± 1.5
Н	4 ± 0.5
N	60
Т	< 14.9

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